

Amendments to the Specification:

[0018] A first preferred embodiment of the present invention involves (1) using one of a diode laser, a diode laser array, an array of light emitting diodes, an IR laser, a fiber laser, a UV laser, a CO₂ laser, or a combination thereof to locally heat the target location, and (2) using one of a UV laser, an IR laser, a green laser, and a CO₂ laser to emit the processing laser output whose incidence on the target material effects removal of target location material to form a hole or via. The via can be either a blind via or a through-hole via. The processing laser output is preferably emitted by a solid-state laser having a wavelength in one of the IR, UV, or green light spectrums. In an alternative preferred implementation, the processing laser output [[it]] is emitted by a CO₂ laser having a wavelength between about 9.2 microns and about 10.6 microns.